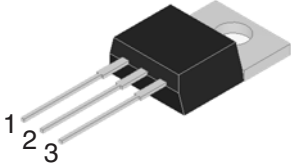
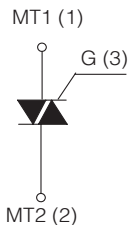




INSULATED LOGIC LEVEL TRIAC

| | | | | | |
|---|---|----------------------------------|---|---|--|
| <p style="text-align: center; font-weight: bold; font-size: 1.2em;">INSULATED TO-220AB</p> <div style="text-align: center; margin: 20px 0;">  </div> <div style="text-align: center; margin: 20px 0;">  </div> | <table style="width: 100%; border-collapse: collapse;"> <tr> <td style="width: 50%; padding: 5px;">On-State Current 8 Amp</td> <td style="width: 50%; padding: 5px;">Gate Trigger Current ≤ 10 mA (08) & (09) ≤ 5 mA (04)</td> </tr> <tr> <td colspan="2" style="text-align: center; padding: 5px;">Off-State Voltage 400 V ÷ 800 V</td> </tr> </table> <p>FEATURES</p> <ul style="list-style-type: none"> • Glass/passivated die junctions • Provides voltage insulated tab (rated at 2500V RMS) • Medium current Triac • Low thermal resistance • High surge current capability • Low forward voltage drop • Solder dip 260°C, 10s • Component in accordance to RoHS 2011/65/EU and WEEE 2002/96/EC • Meets MSL level 3, per J-STD-020, LF maximum peak of 260° C • Certified compliance of UL 1557 Standard for Electrically Isolated Semiconductors. Fille reference E320541, Vol. 3 <p style="text-align: right; margin-right: 20px;">   RoHS COMPLIANT </p> <p>MECHANICAL DATA</p> <ul style="list-style-type: none"> • Case: INSULATED TO-220AB. Epoxy meets UL 94V-0 flammability rating. • Polarity: As marked on the body. • Terminals: Matte tin plated leads, solderable per MIL-STD-750 Method 2026, J-STD-002 and JESD22-B102. Consumer grade, meets JESD 201 class 1A whisker test. <p>TYPICAL APPLICATIONS</p> <p>Logic level versions are designed to interface directly with low power drivers such as microcontrollers.</p> | On-State Current 8 Amp | Gate Trigger Current ≤ 10 mA (08) & (09) ≤ 5 mA (04) | Off-State Voltage 400 V ÷ 800 V | |
| On-State Current 8 Amp | Gate Trigger Current ≤ 10 mA (08) & (09) ≤ 5 mA (04) | | | | |
| Off-State Voltage 400 V ÷ 800 V | | | | | |

Maximun Ratings and Electrical Characteristics at 25°C

| SYMBOL | PARAMETER | CONDITIONS | Value | Unit |
|--------------|---|---|------------|------------------|
| $I_{T(RMS)}$ | RMS On-state Current (full sine wave) | All Conduction Angle, $T_c = 100\text{ }^\circ\text{C}$ | 8 | A |
| I_{TSM} | Non-repetitive On-State Current | Full Cycle, 60 Hz ($t = 16.7\text{ ms}$) | 84 | A |
| I_{TSM} | Non-repetitive On-State Current | Full Cycle, 50 Hz ($t = 20\text{ ms}$) | 80 | A |
| I^2t | Fusing Current | $t_p = 10\text{ ms}$, Half Cycle | 36 | A^2s |
| I_{GM} | Peak Gate Current | $20\text{ }\mu\text{s max.}$ $T_j = 125\text{ }^\circ\text{C}$ | 4 | A |
| $P_{G(AV)}$ | Average Gate Power Dissipation | $T_j = 125\text{ }^\circ\text{C}$ | 1 | W |
| di/dt | Critical rate of rise of on-state current | $I_G = 2 \times I_{GT}$, $t_r \leq 100\text{ ns}$ $f = 120\text{ Hz}$, $T_j = 125\text{ }^\circ\text{C}$ | 50 | $A/\mu\text{s}$ |
| T_j | Operating Temperature | | (-40 +125) | $^\circ\text{C}$ |
| T_{sta} | Storage Temperature | | (-40 +125) | $^\circ\text{C}$ |
| T_{sld} | Soldering Temperature | 10s max | 260 | $^\circ\text{C}$ |
| V_{iso} | R.M.S. isolation voltage 50/60 Hz sinusoidal waveform | | 2.500 | Vac |

| SYMBOL | PARAMETER | VOLTAGE | | | Unit |
|-------------------|-----------------------------------|---------|-----|-----|------|
| | | D | M | N | |
| V_{DRM}/V_{RRM} | Repetitive Peak Off State Voltage | 400 | 600 | 800 | V |

INSULATED LOGIC LEVEL TRIAC

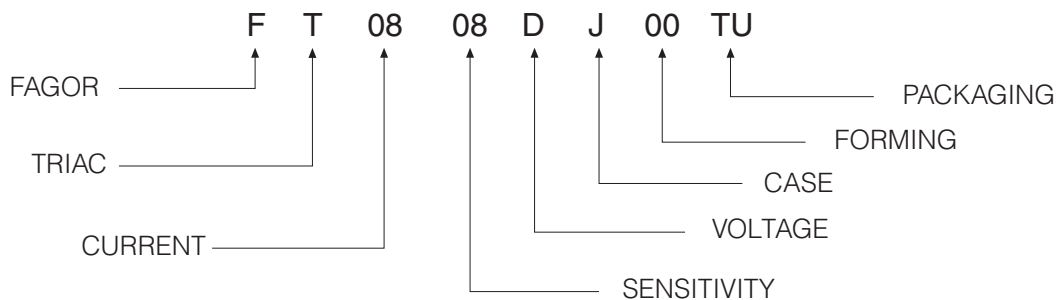
Electrical Characteristics at Tamb = 25 °C

| SYMBOL | PARAMETER | CONDITIONS | Quadrant | | SENSITIVITY | | | Unit |
|-------------------------------------|--|--|-----------|-----|-------------|------|-----|------|
| | | | | | 04 | 08 | 09 | |
| I _{GT} ⁽¹⁾ | Gate Trigger Current | V _D = 12 V _{DC} , R _L = 33Ω, T _j = 25 °C | Q1÷Q3 | MAX | 5 | 10 | 10 | mA |
| | | | Q4 | MAX | - | - | 10 | mA |
| V _{GT} | Gate Trigger Voltage | V _D = 12 V _{DC} , R _L = 33Ω, T _j = 25 °C | Q1÷Q3 | MAX | 1.3 | 1.3 | - | V |
| | | | Q1÷Q4 | MAX | - | - | 1.3 | V |
| V _{GD} | Gate Non Trigger Voltage | V _D = V _{DRM} , R _L = 3.3 KΩ, T _j = 125 °C | Q1÷Q3 | MIN | 0.2 | 0.2 | - | V |
| | | | Q1÷Q4 | MIN | - | - | 0.2 | V |
| I _H ⁽²⁾ | Holding Current | I _T = 100 mA, Gate open, T _j = 25 °C | | MAX | 10 | 15 | 20 | mA |
| I _L | Latching Current | I _G = 1.2 I _{GT} , T _j = 25 °C | Q1,Q3 | MAX | 10 | 25 | - | mA |
| | | | Q2 | MAX | 20 | 30 | 25 | mA |
| | | | Q1,Q3, Q4 | MAX | - | - | 20 | mA |
| dV/dt ⁽²⁾ | Critical Rate of Voltage Rise | V _D = 0.67 x V _{DRM} , Gate open T _j = 125 °C | | MIN | 20 | 40 | 50 | V/μs |
| (dI/dt) _c ⁽²⁾ | Critical Rate of Current Rise | (dv/dt) _c = 0.1 V/μs T _j = 125 °C | | MIN | 3.5 | 5.4 | 3.5 | A/ms |
| | | (dv/dt) _c = 10 V/μs T _j = 125 °C | | MIN | 1.5 | 2.98 | 1.8 | A/ms |
| V _{TM} ⁽²⁾ | On-state Voltage | I _T = 11 Amp, t _p = 380 μs, T _j = 25 °C | | MAX | 1.55 | | | V |
| V _{t(o)} ⁽²⁾ | Threshold Voltage | T _j = 125 °C | | MAX | 0.85 | | | V |
| r _d ⁽²⁾ | Dynamic resistance | T _j = 125 °C | | MAX | 50 | | | mΩ |
| I _{DRM} /I _{RRM} | Off-State Leakage Current | V _D = V _{DRM} , T _j = 125 °C | | MAX | 1 | | | mA |
| | | V _R = V _{RRM} , T _j = 25 °C | | MAX | 5 | | | μA |
| R _{th(j-c)} | Thermal Resistance Junction-Case | for AC 360° conduction angle | | | 2.5 | | | °C/W |
| R _{th(j-a)} | Thermal Resistance Junction-Ambient | | | | 60 | | | °C/W |

(1) Minimum I_{GT} is guaranteed at 5% of I_{GT} max.

(2) For either polarity of electrode MT2 voltage with reference to electrode MT1.

Part Number Information



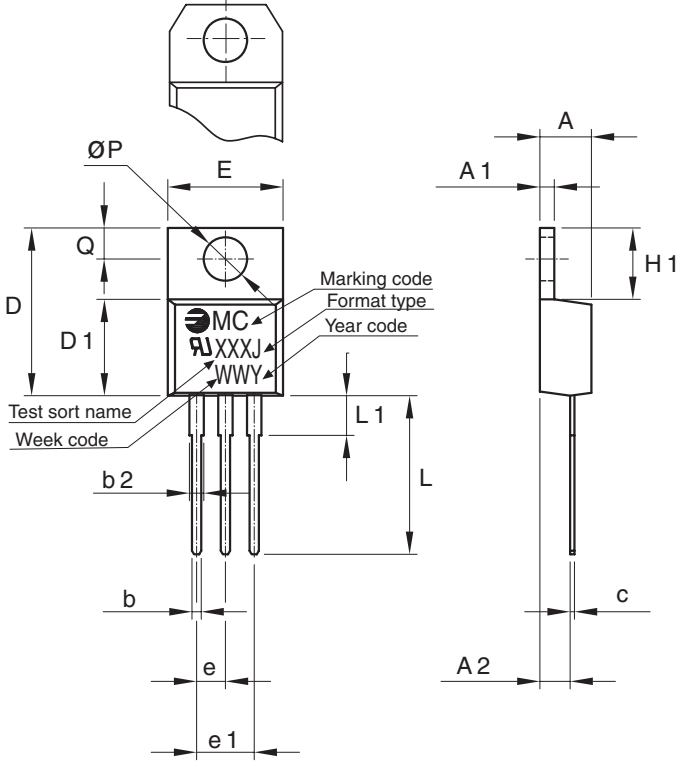
INSULATED LOGIC LEVEL TRIAC

Ordering information

| PREFERRED P/N | PACKAGE CODE | DELIVERY MODE | BASE QUANTITY | UNIT WEIGHT (g) |
|---------------|--------------|---------------|---------------|-----------------|
| FT0808MJ 00TU | TU | TUBE | 1000 | 2.30 |

Package Outline Dimensions: (mm) INSULATED TO-220AB

Optional with chamfer



| REF. | DIMENSIONS | |
|------|-------------|-------|
| | Millimeters | |
| | Min. | Max. |
| A | 4.32 | 4.62 |
| A1 | 1.21 | 1.29 |
| A2 | 2.40 | 2.70 |
| b | 0.80 | 0.83 |
| b2 | 1.40 | -- |
| c | 0.42 | 0.48 |
| D | 15.5 | 15.68 |
| D1 | 9.26 | 9.42 |
| E | 10.08 | 10.24 |
| e | 2.54 | 2.54 |
| e1 | 5.08 | 5.08 |
| H1 | 6.24 | 6.26 |
| L | 12.81 | 13.81 |
| L1 | 3.28 | 4.17 |
| P | 3.70 | 3.80 |
| Q | 2.75 | 2.85 |

Mounting Torque

0.8 N.m

INSULATED LOGIC LEVEL TRIAC

Ratings and Characteristics (Ta 25 °C unless otherwise noted)

Fig. 1: Maximum power dissipation versus RMS on-state current (full cycle).

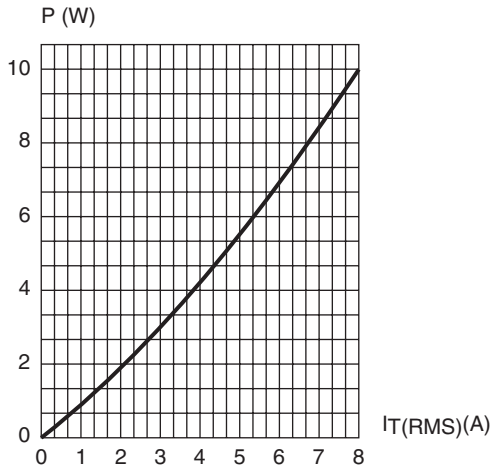


Fig. 2: RMS on-state current versus case temperature (full cycle).

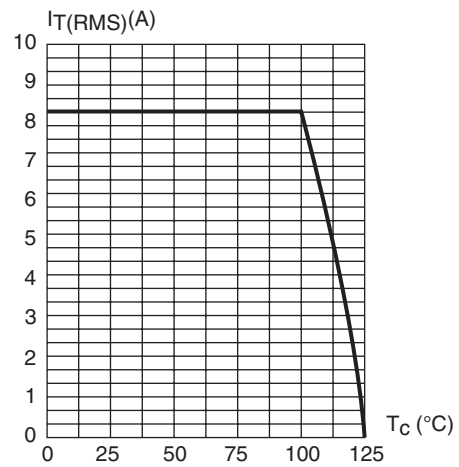


Fig. 3: Relative variation of thermal impedance versus pulse duration.

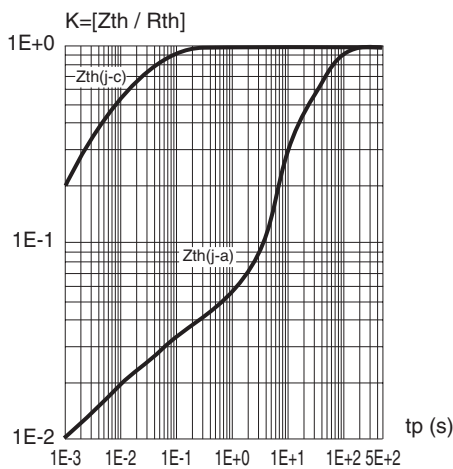


Fig. 4: On-state characteristics (maximum values)

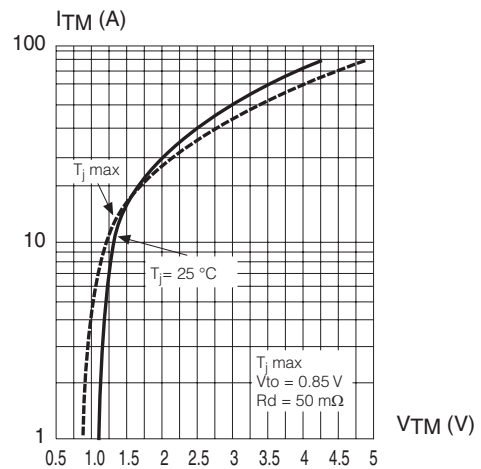


Fig. 5: Surge peak on-state current versus number of cycles

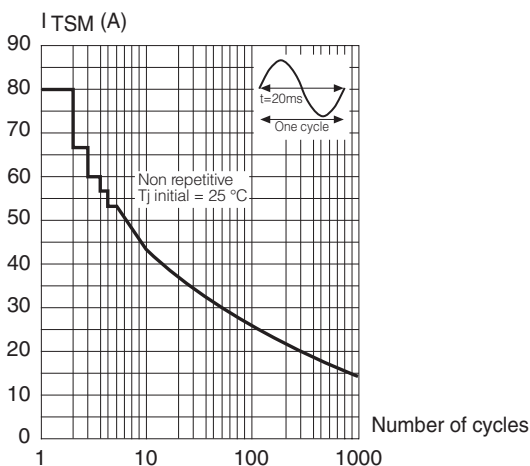
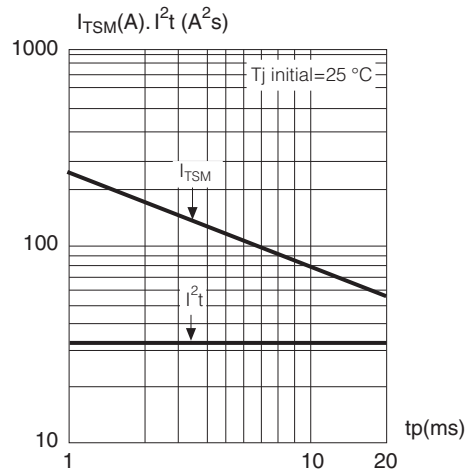


Fig. 6: Non repetitive surge peak on-state current for a sinusoidal pulse with width: tp < 10 ms, and corresponding value of I²t.



INSULATED LOGIC LEVEL TRIAC

Ratings and Characteristics (Ta 25 °C unless otherwise noted)

Fig. 7: Relative variation of gate trigger current, holding current and latching versus junction temperature (typical values)

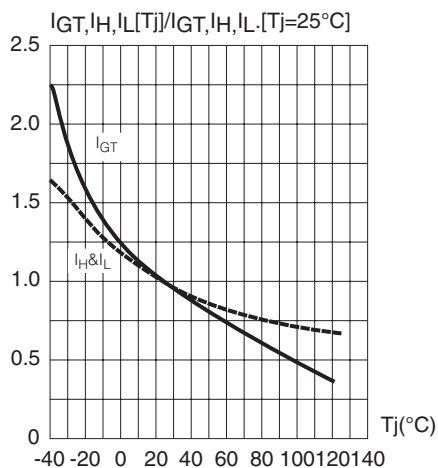


Fig. 8: Relative variation of critical rate of decrease of main current versus junction temperature

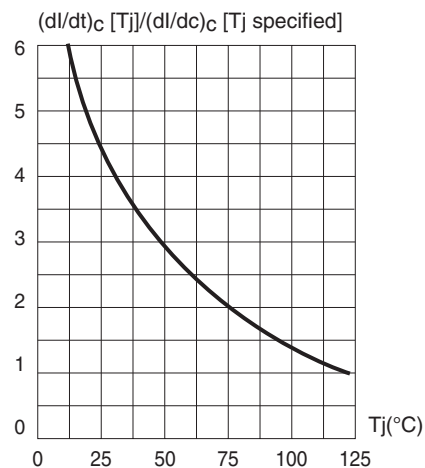
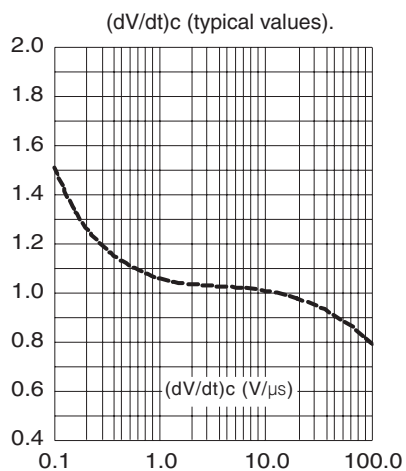


Fig. 9: Relative variation of critical rate of decrease of main current versus $(dV/dt)_c$ (typical values).



INSULATED LOGIC LEVEL TRIAC

Revision History

| Date | Revision | Description of Changes |
|-------------|----------|---|
| 15-Oct-2012 | 0 | Original Data Sheet |
| 27-Jan-2016 | 1 | Updated IL Q2 for 04 group of sensitivity |
| 31-Mar-2017 | 2 | 200V eliminated |

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